



**TF Semiconductor  
Solutions**

# **TF Products Logistics Guide**

## **Spring 2021**

# Package Codes

## Ordering Codes

**TFxxxx-PPZ**

Device Function

Package Code

Pack Form

(Tube or T&R)

\* Dry Pack

## Package and Pack Codes

Package Name	Abbreviated Package Name	Pin Count	Package Code	Tube Mark Code	Tube Pack Quantity	Tray Mark Code	Tray Pack Quantity	180 mm Code	180 mm Pack Quantity	330 mm Code	330 mm Pack Quantity
Plastic Dual In-line Package Narrow	PDIP (N)	8	3A	S	50						
	PDIP (N)	14	3B	S	25						
	PDIP (N)	16	3E								
	PDIP (N)	22	3H	S	18						
Small Outline IC Narrow	SOIC (N)	8	TA	S / U*	95			P / G*	1000	Q / H*	2500
	SOIC (N)	14	TU	S / U*	54					Q / H*	2500
	SOIC (N)	16	TB	S / U*	48			P / G*	500	Q / H*	2500
Small Outline IC Wide	SOIC (W)	16	TE	U*	47					H*	2500
	SOIC (W)	20	TG								
	SOIC (W)	28	TL								
Small Outline IC Narrow w/ Exposed Pad	SOIC (N)-EP	8	TP	S	95			P	1000	Q	2500
	SOIC (N)-EP	16	TR	S	48						
Thin Shrink Small Outline Package	TSSOP	14	6B								
	TSSOP	16	6C	U*	94			G	1000		
Small Outline Transistor Package	SOT23	3	UR					P	3000	Q	10000
	SOT23	5	US					P	3000	Q	10000
	SOT23	6	UT					P	3000	Q	10000
SC70 Transistor Package	SC70	3	XR					P	3000	Q	10000
	SC70	5	XS					P	3000	Q	10000
	SC70	6	XT					P	3000	Q	10000
Dual / Quad Flatpack, Leadless	DFN 2x3	2x4	ND					P	3000	Q	10000
	DFN 2x2	2x4	NB	S	120			P	3000	Q	10000
	DFN 3x3	2x5	NH	S	120			P	3000	Q	10000
	DFN 4x3	2x7	NF					P	1000	Q	3000
	QFN 4x4	4x6	NE								
	QFN 7x7	4x11	NC	U*	52			G*	1000		
Quad Flatpack, Leads	TQFP	4x25	PB			V*	90				
Ball Grid Array	BGA	10x10	BB			V*	240				
Evaluation Board	EVK										
Mini Small Outline Package	MSOP	10	MK		100						3000

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# Package Dimensions

**TFxxxx-PPZ**

Device Function | Package Code | Pack Form (Tube or T&R)

## Package Dimensions

\* Dry Pack

Package Name	Abbreviated Package Name	Pin Count	Package Code	Lead / Ball Pitch (mm)	Package Length L (mm)	Package Width W (mm)	Package Thickness T (mm)
Plastic Dual In-line Package Narrow	PDIP (N)	8	3A	2.54	9.80	6.30	3.60
	PDIP (N)	14	3B	2.54	20.00	6.30	3.60
	PDIP (N)	16	3E	2.54	20.00	6.30	3.60
	PDIP (N)	22	3H	5.54	26.25	6.30	3.60
Small Outline IC Narrow	SOIC (N)	8	TA	1.27	4.90	3.90	1.45
	SOIC (N)	14	TU	1.27		3.90	1.45
	SOIC (N)	16	TB	1.27	9.90	3.90	1.45
Small Outline IC Wide	SOIC (W)	16	TE	1.27	10.30	7.47	2.50
	SOIC (W)	20	TG	1.27	12.80	7.47	2.50
	SOIC (W)	28	TL	1.00	18.30	8.40	3.00
Small Outline IC Narrow w/ Exposed Pad	SOIC (N)-EP	8	TP	1.27	4.90	3.90	1.45
	SOIC (N)-EP	16	TR	1.27	9.90	3.90	1.45
Thin Shrink Small Outline Package	TSSOP	14	6B	0.65	5.00	4.40	0.90
	TSSOP	16	6C	0.65	5.00	4.40	0.90
Small Outline Transistor Package	SOT23	3	UR	1.91	2.92	1.30	0.93
	SOT23	5	US	0.95	2.92	1.60	1.02
	SOT23	6	UT	0.95	2.92	1.60	1.02
SC70 Transistor Package	SC70	3	XR	1.30	2.00	1.25	0.90
	SC70	5	XS	0.65	2.00	1.25	0.90
	SC70	6	XT	0.65	2.00	1.25	0.90
Dual / Quad Flatpack, Leadless	DFN 2x3	2x4	ND	0.50	2.00	1.25	0.90
	DFN 2x2	2x4	NB	0.50	2.00	1.25	0.90
	DFN 3x3	2x5	NH	0.50	2.00	2.00	0.75
	DFN 4x3	2x7	NF	0.50	4.00	3.00	0.75
	QFN 4x4	4x6	NE				
	QFN 7x7	4x11	NC	0.50	7.00	7.00	0.90
Quad Flatpack, Leads	TQFP	4x25	PB	0.50	14.00	14.00	1.00
Ball Grid Array	BGA	10x10	BB	0.80	10.00	10.00	1.40
Mini Small Outline Package	MSOP	10	MK	0.50	4.90	3.00	1.10

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# Product Mark

## ALL PACKAGES $\geq$ 4.9mm X 3.9mm (SOIG8)

Line 1: Date Code  
 Line 2: Product Name (up to 10 total characters)  
 Line 3: Lot Identifier

TF Logo



YYWW  
 1403 = Year 2014, Week 03

## 7X7 QFN/DFN

Line 1: Date Code  
 Line 2: Product Name (up to 8 total characters)  
 Line 3: Lot Identifier

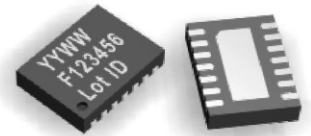
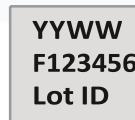
TF Logo



## 4X3 QFN/DFN

Line 1: Date Code  
 Line 2: Product Name (up to 7 total characters)  
 Line 3: Lot Identifier

No Logo



## 2X3, 2X2 QFN/DFN

Line 1: Date Code (Year, **W** Week as per table), and Lot Identifier  
 Line 2: Product Name (3 Character Code established by TF Semi)

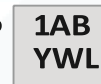
No Logo



WorkWeek	Date Code Week	WorkWeek	Date Code Week	WorkWeek	Date Code Week	WorkWeek	Date Code Week
VW01	A	VW14	N	VW27	a	VW40	n
VW02	B	VW15	O	VW28	b	VW41	o
VW03	C	VW16	P	VW29	c	VW42	p
VW04	D	VW17	Q	VW30	d	VW43	q
VW05	E	VW18	R	VW31	e	VW44	r
VW06	F	VW19	S	VW32	f	VW45	s
VW07	G	VW20	T	VW33	g	VW46	t
VW08	H	VW21	U	VW34	h	VW47	u
VW09	I	VW22	V	VW35	i	VW48	v
VW10	J	VW23	W	VW36	j	VW49	w
VW11	K	VW24	X	VW37	k	VW50	x
VW12	L	VW25	Y	VW38	l	VW51	y
VW13	M	VW26	Z	VW39	m	VW52	z

Line 1: Product Name (3 Character Code established by TF Semi)  
 Line 2: Date Code (Year, **W** Week as per table), and Lot Identifier

No Logo



WorkWeek	Date Code Week	WorkWeek	Date Code Week	WorkWeek	Date Code Week	WorkWeek	Date Code Week
VW01	A	VW14	G	VW27	N	VW40	T
VW02	B	VW15	H	VW28	O	VW41	U
VW03	C	VW16	I	VW29	P	VW42	V
VW04	D	VW17	J	VW30	Q	VW43	W
VW05	E	VW18	K	VW31	R	VW44	X
VW06	F	VW19	L	VW32	S	VW45	Y
VW07	G	VW20	M	VW33	T	VW46	Z
VW08		VW21		VW34		VW47	
VW09		VW22		VW35		VW48	
VW10		VW23		VW36		VW49	
VW11		VW24		VW37		VW50	
VW12		VW25		VW38		VW51	
VW13		VW26		VW39		VW52	

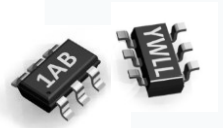
# Product Mark

## SOT, SC70

TOP: Product Name (3 Character Code established by TF Semi)

BOTTOM: Date Code (Year, **W**Week as per table), and Lot Identifier

TOP **1AB**  
BOTTOM **YWLL**



Reference Table: Definition of single **W** format.

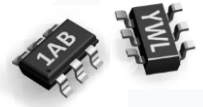
WorkWeek	Date Code Week	WorkWeek	Date Code Week	WorkWeek	Date Code Week	WorkWeek	Date Code Week
VW01	A	VW14	N	VW27	a	VW40	n
VW02	B	VW15	O	VW28	b	VW41	o
VW03	C	VW16	P	VW29	c	VW42	p
VW04	D	VW17	Q	VW30	d	VW43	q
VW05	E	VW18	R	VW31	e	VW44	r
VW06	F	VW19	S	VW32	f	VW45	s
VW07	G	VW20	T	VW33	g	VW46	t
VW08	H	VW21	U	VW34	h	VW47	u
VW09	I	VW22	V	VW35	i	VW48	v
VW10	J	VW23	W	VW36	j	VW49	w
VW11	K	VW24	X	VW37	k	VW50	x
VW12	L	VW25	Y	VW38	l	VW51	y
VW13	M	VW26	Z	VW39	m	VW52	z

## Priortodatecode 1X (Dec 1<sup>st</sup>, 2011)

TOP: Product Name (3 Character Code established by TF Semi)

BOTTOM: Date Code (Year, **W**Week as per table), and Lot Identifier

TOP **1AB**  
BOTTOM **YWL**



Reference Table: Definition of single **W** format.

WorkWeek	Date Code Week	WorkWeek	Date Code Week	WorkWeek	Date Code Week	WorkWeek	Date Code Week
VW01		VW14	<b>G</b>	VW27	<b>N</b>	VW40	<b>T</b>
VW02	<b>A</b>	VW15	<b>H</b>	VW28	<b>O</b>	VW41	<b>U</b>
VW03		VW16	<b>I</b>	VW29	<b>P</b>	VW42	<b>V</b>
VW04	<b>B</b>	VW17	<b>J</b>	VW30	<b>Q</b>	VW43	<b>W</b>
VW05		VW18	<b>K</b>	VW31	<b>R</b>	VW44	<b>X</b>
VW06	<b>C</b>	VW19	<b>L</b>	VW32	<b>S</b>	VW45	<b>Y</b>
VW07		VW20	<b>M</b>	VW33	<b>T</b>	VW46	<b>Z</b>
VW08	<b>D</b>	VW21		VW34		VW47	
VW09		VW22		VW35		VW48	
VW10	<b>E</b>	VW23		VW36		VW49	
VW11		VW24		VW37		VW50	
VW12	<b>F</b>	VW25		VW38		VW51	
VW13		VW26		VW39		VW52	

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## Package Reference Data

Package	Pin Count	SAP Code	Lead/ Ball Pitch (mm)	Package Length L (mm)	Package Width W (mm)	Package Thickness T (mm)	TF Semi Devices (Ordering Code Examples)
PDIP (N)	8	3A	2.54	9.8	6.3	3.6	TF2101-3AS, TF2103-3AS, TF2103A-3AS, TF2104-3AS, TF2104A-3AS, TF2190-3AS, TF2184-3AS, TF2117/2118-3AS, TF2106-3AS, TF2108-3AS, TF2181-3AS, TF1304-3AS
PDIP (N)	14	3B	2.54	20.0	6.3	3.6	TF2110-3BS, TF2113-3BS, TF21064-3BS, TF21084-3BS, TF21814-3BS, TF21844-3BS
PDIP (N)	16	3E	2.54	20.0	6.3	3.6	
PDIP (N)	18	3F	2.54	23.3	6.3	3.6	
PDIP (N)	20	3G	2.54	26.6	6.3	3.6	
SOIC (N)	8	TA	1.27	4.9	3.9	1.45	TF2101-TAU, TF2103-TAU, TF2103A-TAU, TF2104-TAU, TF2104A-TAU, TF2190-TAU, TF2184-TAU, TF2117/2118TAU, TF2106-TAU, TF2108-TAU, TF2181-TAU, TF1304-TAU, TF6001-TAU, TF6002-TAU, TF1503-TAU, TF1504-TAU
SOIC (N)	14	TU	1.27	8.64	3.9	1.45	TF21064-TUU, TF21084-TUU, TF21814-TUU, TF21844-TUU
SOIC (N)	16	TB	1.27	9.91	3.9	1.45	
SOIC (W)	16	TE	1.27	10.3	7.47	2.5	TF2110-TEU, TF2113-TEU
SOIC (W)	20	TG	1.27	12.8	7.47	2.5	
SOIC (W)	28	TL	1.27	18.0	7.47	2.5	TF23892-TLU, TF1692-TLU, TF0692-TLU, TF2136-TLU, TF1636-TLU, TF0636-TLU
SOIC (N)-EP	8	TP	1.27	4.90	3.9	1.45	TF6003-TPU
SOIC (N)-EP	16	TR	1.27	9.91	3.9	1.45	
TSSOP	14	6B	0.65	5.0	4.4	0.9	
TSSOP	16	6C	0.65	5.0	4.4	0.9	TF90LVDS047-6CU, TF90LVDS048-6CU
SOT23	3	UR	1.91	2.92	1.3	0.93	
SOT23	5	US	0.95	2.92	1.6	1.02	
SOT23	6	UT	0.95	2.92	1.6	1.02	TF4601A-UT45U, TF4601B-UT20U, TF4602-UT28U
SC70	3	XR	1.3	2.0	1.25	0.9	
SC70	5	XS	0.65	2.0	1.25	0.9	
SC70	6	XT	0.65	2.0	1.25	0.9	
QFN	4x2	NA	0.5	2.0	2.0	0.9	

QFN	2x4	NB	0.5	2.0	2.0	0.9	TF4601A-NB45U, TF4601B-NB20U
Package	Pin Count	SAP Code	Lead/ Ball Pitch (mm)	Package Length L (mm)	Package Width W (mm)	Package Thickness T (mm)	TF Semi Devices (Ordering Code Examples)
TDFN	2x5	NH	0.5	3.0	3.0	0.75	TF0503-NHS, TF0504-NHS, TF0506-NHS, TF0507-NHS
TQFP	4x16	PA	0.5	10.0	10.0	1.0	
TQFP	4x25	PB	0.5	14.0	14.0	1.0	TF112-PBU
BGA	8x8	BA	0.80	8.0	8.0	1.4	
BGA	10x10	BB	0.80	10.0	10.0	1.4	TF112-BBU

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